

# NAVOLCHI

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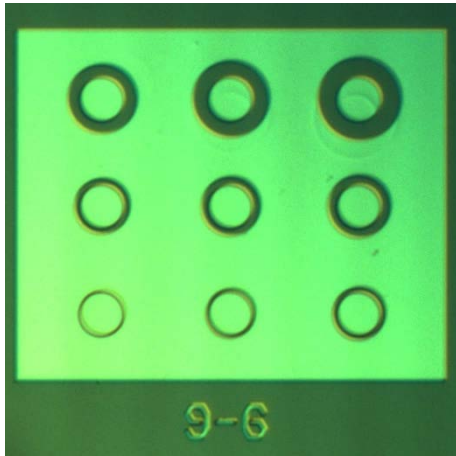
**TU** / **e**

Technische Universiteit  
**Eindhoven**  
University of Technology

**Where innovation starts**

# Circular TLM to measure contact resistance

- Experiment



- Layer stack

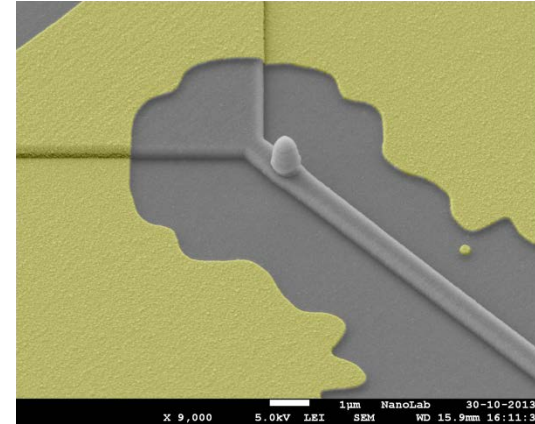
Ag (300 nm)
Ge (2, 15 nm)
InGaAs (100 nm) $N > 1e19$ 1/cm <sup>3</sup>
N-InP

- Results:

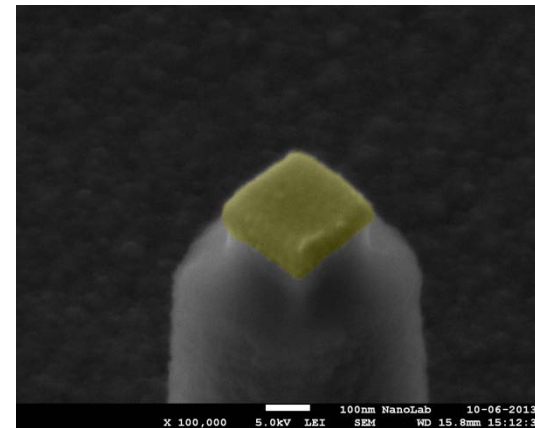
Recipe	$\rho_c$ [ $\Omega$ cm <sup>2</sup> ]
Recipe 1	1.3e-7
Recipe 2	<b>5.9e-8</b>
Recipe 3	1.8e-7
Recipe 4	4.1e-7

# Silver contacts → Simplify fabrication

- No need for adhesion pads



- No need for critical planarization to deposit ohmic contacts

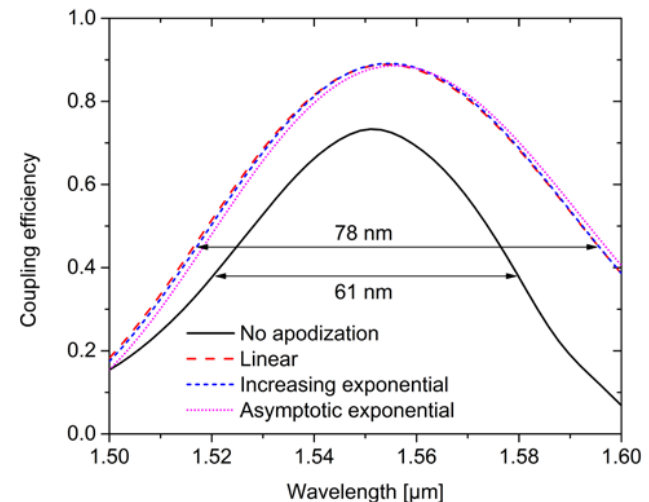
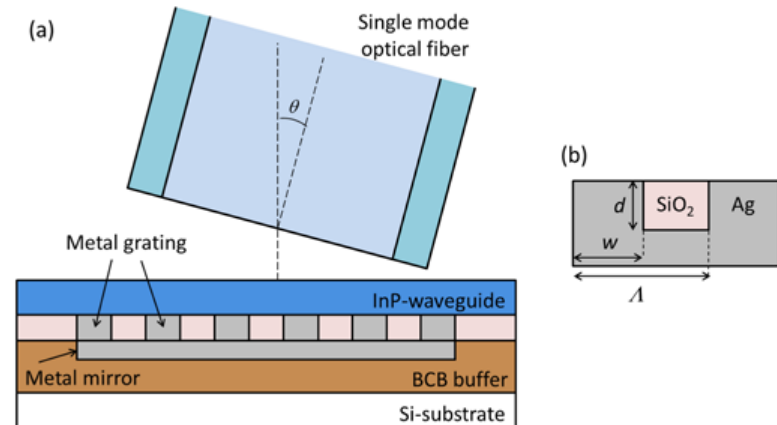


# News regarding laser

- I recently got 2 new wafers (last week) for a new run
- Managed to partially solve BCB gassing issue, at the expense of a lower outcoupling efficiency of grating couplers. **Real problem remains unsolved.**
  - Did UGhent make experiments in this respect?
- Planning etching tests of pillars in bonded (III-V on Si) samples → Planning a new run of lasers

# Metal grating coupler

- Advantages
  - High efficiency:  
73%  $\rightarrow$  89%(apodized)
  - **Independence from buffer thickness**
- US provisional patent application filed



Highly efficient metal grating coupler for membrane-based integrated photonics, V. Dolores Calzadilla, D. Heiss, M. Smit, *Optics Letters* 39(9), 2014.